

Capital Market Days 2011 August 23 - 24

Oerlikon Advanced Technologies Andreas R. Dill

August 24, 2011



Agenda



- 1 Did you know?
- 2 Technological Leadership
- 3 Markets & Customers
- 4 Operational Excellence
- 5 Tactics & Financials
- 6 Summary

Did you know?



Solaris

Cell Phones

Harddisks



Highest productivity tool for crystalline photovoltaics and other clean tech applications



Most cell phones see, hear or transmit through thin films produced with Oerlikon technology



Today 50% of all read/write heads for hard disks use Oerlikon thin film technology

Did you know?



Play Station



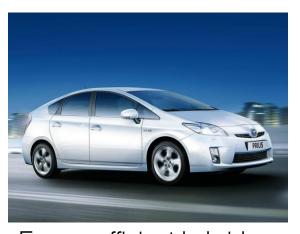
More than 80% of all microprocessors work with Oerlikon technology.

Solar Modules



Leading manufacturers use Oerlikon Systems for high volume production of crystalline solar cells.

Energy saving



Energy efficient hybrid cars and power supplies for any electrical appliance depend on power devices manufactured with Oerlikon high volume production technology

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Oerlikon Advanced Technologies operates in three main markets and serves as R&D incubator for the Oerlikon Group

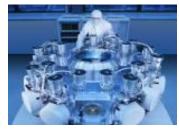
Semiconductors



200/300

LLS

Optical Disc



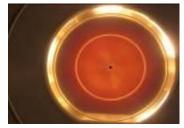
Sprinter, Swivel, CubeStar

Advanced Nanotechnology



Solaris

R&D Incubator for Oerlikon



R&D Pilots and Demonstrators

Products

- **Applications** Adv/3D Packaging
 - Thin Wafer and Multi-Level Metal
 - LED lighting
 - TFH, MEMS, NEMS
 - Compound Semi

- Blu-Ray Media
- All DVD formats
- Photovoltaics
 - Thermoelectric generators

Touch Panels

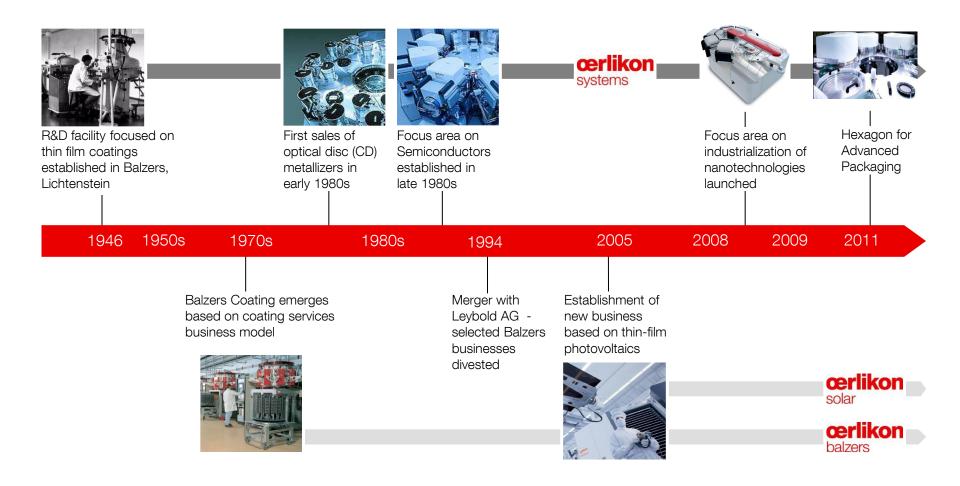
- Energy conversion
- Energy storage
- Energy efficiency management

Strategy

- Differentiation with superior technology in selected markets
- Focus on Blu-Ray Recordable
- Clean Technology
- Incubator

Core competence in and proven 50+ year track record of creating new businesses by industrializing thin film coating applications





Oerlikon Advanced Technologies



Advanced Packaging



High productivity processes meet the highest reliability requirements for the last process step on the wafer level

Energy Efficiency Management

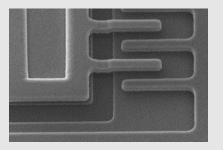
Power Devices LEDs



Best in class temperature management for stressfree metallization films on wafers thinner than 100µm without carrier Best Cost of Ownership tools for various process steps in LED manufacturing

Energy Efficiency Management

Micro Electro Mechanical Systems



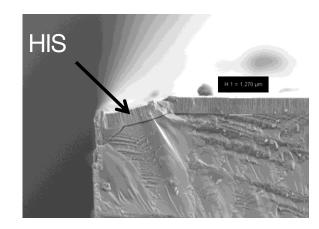
Superior material performance data for high volume production (e.g. 1,5x the piezoelectric deformation factor than any other process)

Leadership in Source and Process Technology



Highly Ionized Sputtering source

- Best performing PVD films for hard coatings (denser, thinner, longer lifetime)
- 3 dimensional coatings of nano structures for Semiconductor applications





PECVD Technology for Solar

- PECVD is the key technology for Thin Film Solar applications
- R&D reactor improvements with increased rate
- 3 dimensional coatings of nano structures for Semiconductor applications like Advanced Packaging (3D)



Hexagon for Advanced Packaging Market



Semiconductor equipment to significantly outperform on performance and price

Highest Productivity

- Integration of best existing high throughput (Solaris), high film performance concepts, and components (sources, wafer chucks)
- Highest maintenance free production time
- Reduced footprint, improved availability and throughput

Lowest risk for customers

- Main process components used in previous platform
- Production proved indexer type handling concept
- Minimum process requalification

Lead time reduction

- Meets requirements of shorter investment cycles
- Reduced installation and production ramp up time

Ready for the future

 Next generation products already qualified



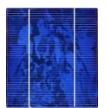
Technological leadership in crystalline PV: PVD for Antireflective Coatings



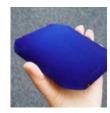
- Single and Multi Crystalline Substrates
- Solaris for antireflective coating with PVD
- This layer serves to limit reflection of incident light and maximize that which enters the device itself
- Surface defects on the wafer itself are also passivated by the hydrogen involved in the film growth process



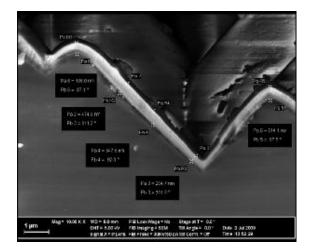


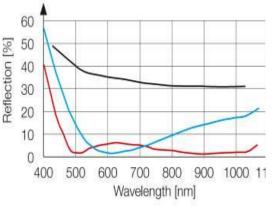


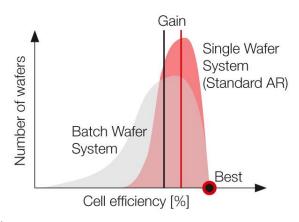












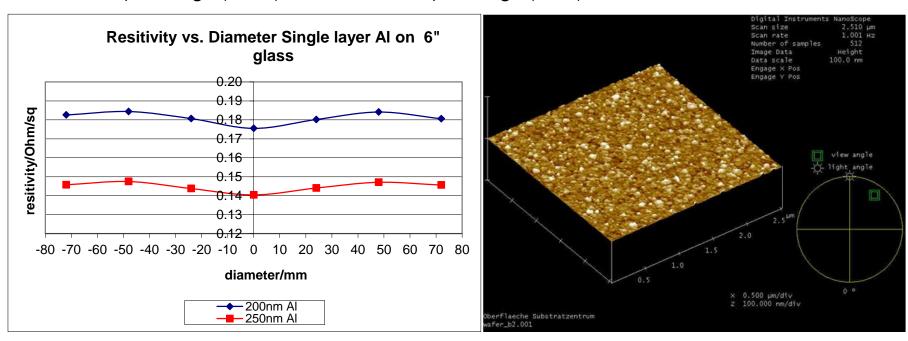
Improvement of cell efficiency by layer stacking

Technological leadership in crystalline PV: Higher Efficiency Cells



High flexibility for advanced cell concepts

- ITO layers for Hetero Junction Cells
- Backside metallization
- Metal-wrap-through (MWT) and Emitter-wrap-through (EWT)



Excellent homgenous ITO layer w/o spikes

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Key products and applications Semiconductor



Key Semi Products / Systems



CLUSTERLINE Platform (CLN 200, CLN 300)



LLS EVO II

Application examples

Segment

Application

Compound Semiconductors



- Solid State Lighting
- LED, Laser

Compound Semiconductors / Advanced packaging



- SAW-, BAW filter
 - Wireless Appl.

Thin Film Head **MEMS**



Thin Film Heads in HDD

Advanced packaging



Microprocessors, memory

Thin Wafer and Multi-level Metallization / **MEMS**



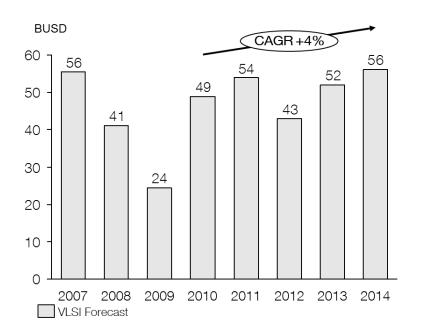
- Power Devices
- Sensors and Actuators

Semiconductor equipment market forecast



Semiconductor Equipment Market

Industry Indicator: Equipment Market VLSI (June 2011)



Strong Position in

- Device stacking (3D) will push the Advanced Packaging market volume to USD 1bn by 2016
- Energy Efficiency: Oerlikon has a very strong position with key manufacturers for Power devices and LED's
- Information and data exchange and personal computing storage capacity requirements ensure solid growth in the harddisk market

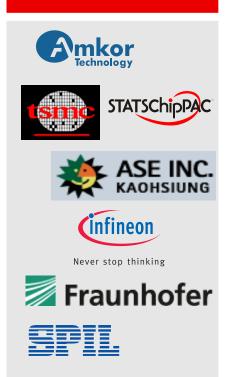
Customers served in Semiconductors



Advanced Packaging

Thin Wafer and Multi-Level Metallization Thin Film Head MEMS

Compound Semiconductors









BD Recordable: Manufactured on Systems **Metallizers**



All major brands rely on Systems Sprinter to produce the critical layer stack

Panasonic

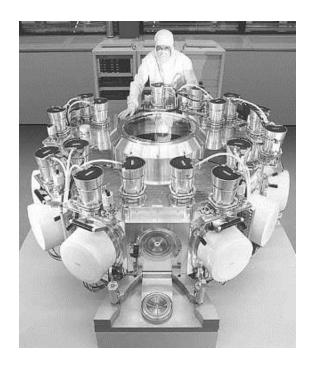














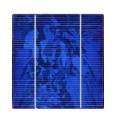


Advanced Nanotechnology as building block for innovations



Energy Conversion

- Solar cells
- Thermoelectric generators
- **Energy Harvesting**

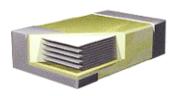




Energy Storage

- Thin Film Batteries
- Fuel cells*
- Micro fuel cells *

*under evaluation



Solaris



- Touch screens
- OLED, SSL
- MEMS / NEMS
- Micro Sensors

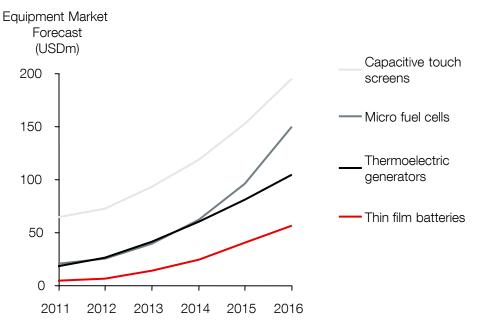




Growth drivers: Clean energy and technology leadership



Advanced Nanotechnology Equipment Demand



Sources:

- Capacitive Touch Panels: iSupply
- Micro Fuel Cells: EET
- Thermoelectric Generators: O-Flex
- Thin Film Batteries: ST Microelectronics

Comments

- Three main drivers are behind the increasing demand for clean and small/lightweight energy:
 - (1) increasing environmental awareness of energy consumers,(2) government subsidization of
 - clean energy solutions, and
 (3) a trend toward smaller and more
 - independent energy supplies for hand-held and other mobile electronics
- Consumer electronics and energy companies face intense competition, making operational excellence and energy efficiency a must

Solaris for crystalline photovoltaics



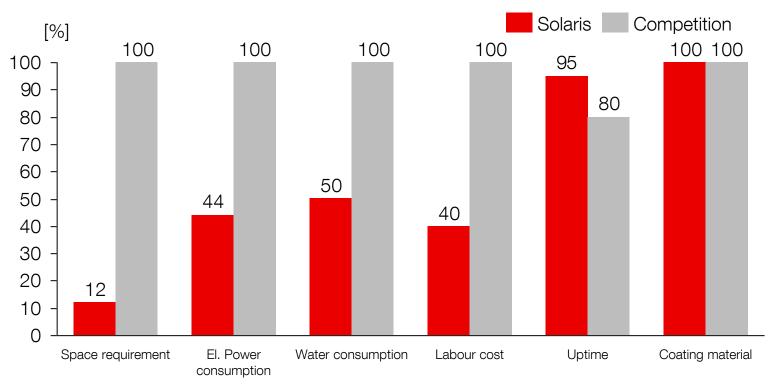
Silane-free PVD process solution for crystalline solar cell manufacturing



- Lowest Cost of Ownership (CoO)
- Processes: Anti-reflective-coating (ARC) / Passivation / Back Side coating, transparent conductive coating (ITO)
- Higher cell efficiency possible due to multilayer capability
- Easy automation and flexible production
- Lowest maintenance and efficient operation
- Silane-free

Solaris for crystalline photovoltaics



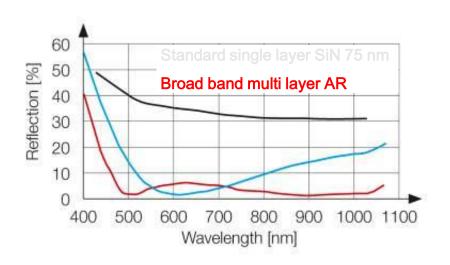


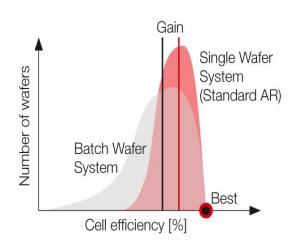
Lowest Cost of Ownership and highest yield

- > 95% Uptime / scheduled preventive maintenance less than 60 min/week
- > 99% Yield
- 80% less footprint required
- 50% less energy consumption
- Productivity: 1200 wafers/hour

Solaris for crystalline photovoltaics







Increased cell efficiency and process stability

- Multi-layer broadband coatings increase cell efficiencies
- + 2% layer uniformity within one wafer, 2.5% wafer to wafer
- Smallest spread between average and best cell efficiencies
- Better process reproducibility as compared to batch due to single wafer process

Video Solaris





Customer Satisfaction - Reputation



Best Supplier Award from world's largest Advanced Packaging foundry ASE (2009 and 2010)



- Awarded exclusively to 1 supplier each year for overall support and technology achievements.
- 2nd year ASE has established this award

VLSI 5 Star Award (2009 and 2010)



- Awarded to only 11 companies in 2010 (Dec 1, 2010)
- CoO, Quality, performance, technical leadership and overall customer satisfaction

VLSI 10 Best Award Number One Position



- High Build Quality
- Field engineering support
- Product performance
- Commitment to meeting customer's needs

Best PV Tool
Solar Industry Award 2010



- Winner was selected by entire PV industry (vote by users, analysts and editors)
- 40% lead over runner-up

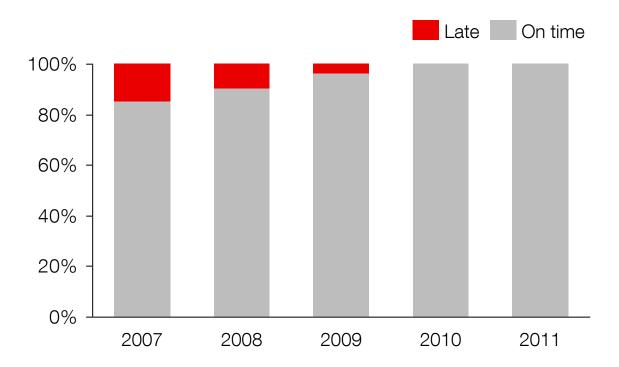
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Business Excellence OTD to Customers



- All year-to-date System deliveries on-time as promised to the customer
- Last late system delivery was in April 2009

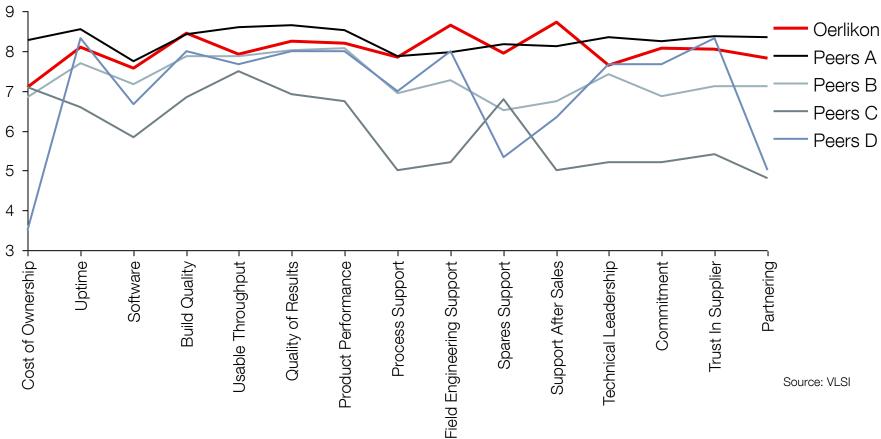
Installed processes:

- Weekly cross-functional planning meetings for projects and retrofits
- Weekly detailed task tracking meetings for all critical projects



Business Excellence Peer Comparison – Quality Leader among main competitors

Customer Satisfaction for Deposition Equipment



- Oerlikon: best in class in build quality, process support, field engineering and after-sales support
- No. 1 or No. 2 position in all major criteria

Agenda

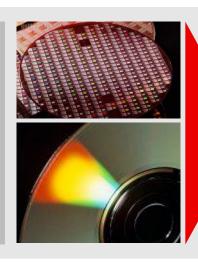


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Tactics for Semiconductor, Optical Disc and Advanced Nanotechnologies

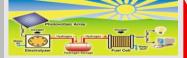


Semiconductor & Optical Disc



- Lean efficient organization
- Cost reduction and operational excellence
- Focus less is more
- Strategic project selection

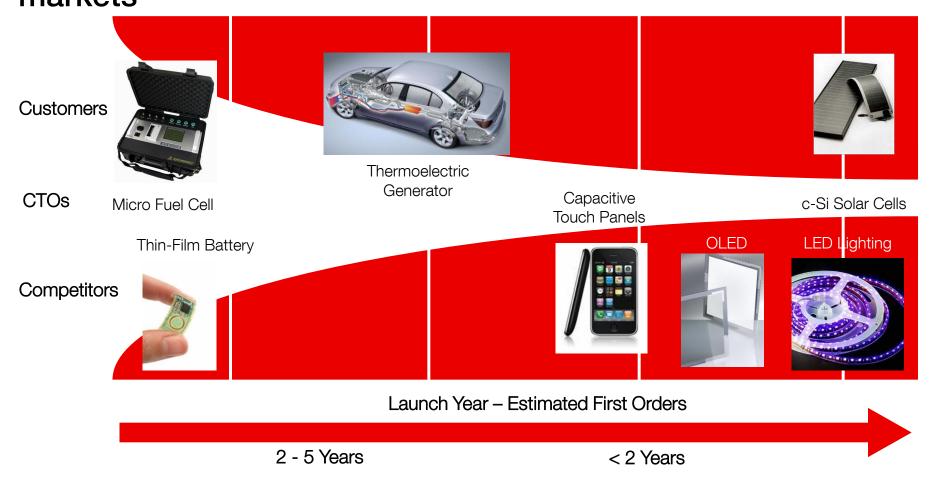
Advanced Nanotechnologies



- New markets existing customers
- New customers
- Focus less is more
- High volume, licensing or contract
 R+D

Strong technology pipeline lays foundation for next success stories in selected high growth markets





Accelerate Advanced Nanotechnology innovations

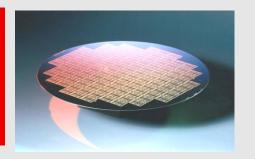


Market Application		Device Market	Equipment Market	5 Year Trend
Energy Conversion	Solar cellsThermoelectric generatorsEnergy Harvesting	20-100 BUS\$	10-20 BUS\$	
Energy Storage	Thin Film BatteriesFuel cellsMicro fuel cells	1-3 BUS\$	0-2 BUS\$	
Energy Efficiency Management	Touch screensOLED, SSLMEMS / NEMSMicro Sensors	1-10 BUS\$	1-3 BUS\$	

Strategic Markets



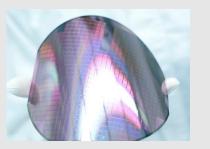
Advanced Packaging – 3D



Market leader and technology enabler for next generation products with the highest productivity solutions

Energy Efficiency Management

Power Devices LEDs

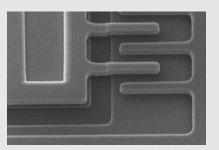


The only company which processes ultra thin wafers without carrier

Provides all types of contact and barrier materials for LED with extension plan of this application

Energy Efficiency Management

Micro Electro Mechanical Systems



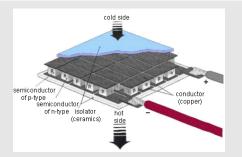
Expand extensive process portfolio (metals, oxides, nitrides, magnetic, piezo, compounds) for all different kinds of sensors, actuators and energy harvesting devices

Strategic Markets



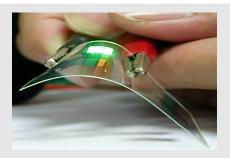
Energy Conversion

Thermoelectric Generator



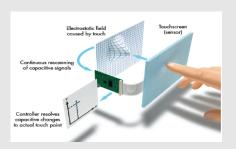
Conversion of waste heat into electricity; Thin Film technology enables commercially viable manufacturing

Energy Storage
ThinFilm Battery



Smart Cards, high-end RFID tags, autonomous sensors, medical implant require higher number of charge cycles. Cost effective manufacturing of thin film lithium batteries with LLS

Energy Efficiency
Management
Capacitive Touch
Screens

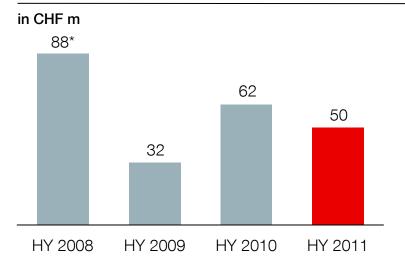


New generation of small form factor touch screens for intelligent mobility devices; highest productivity with lowest Cost of Ownership with Solaris

Order Intake negatively impacted by sharp decline in Optical Disk market (Blu-ray)



Oerlikon Advanced Technologies Order Intake 2008 – HY 2011



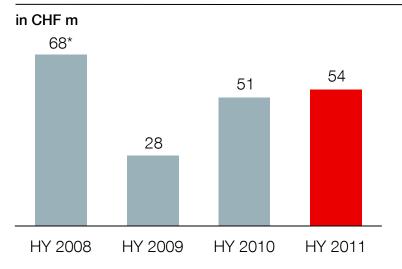


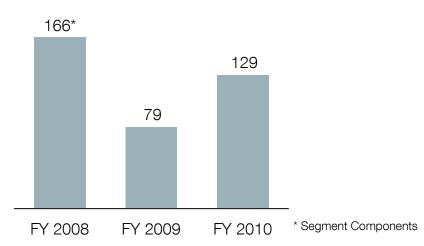
- First Solaris volume order for crystalline PV cells received in 2009
- Semiconductor business was main driver for increase in 2010
- Positive trend from Semiconductor business continued in HY 2011
- Decline in order intake in HY 2011 compared to HY 2010 related to Optical Disc business; no investments in Blu-ray production capacities in HY 2011
- Softening demand for Semiconductor equipment expected in H2 2011; recovery of Optical Disc business expected in H1 2012

Strong HY sales driven by investments in Semiconductor production equipment



Oerlikon Advanced Technologies Sales 2008 – HY 2011

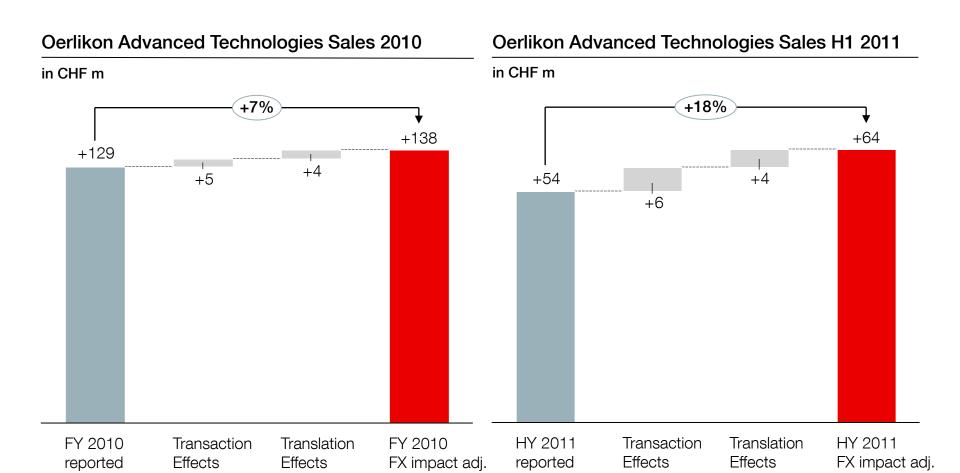




- Semiconductor business was main driver for recovery in 2010 and the first Solaris volume order for crystalline PV cells was successfully executed in 2010
- Semiconductor and Customer Support business are the main contributors to the higher sales compared to HY 2010.

Transaction effects due to production in Swiss Francs significantly affects Sales





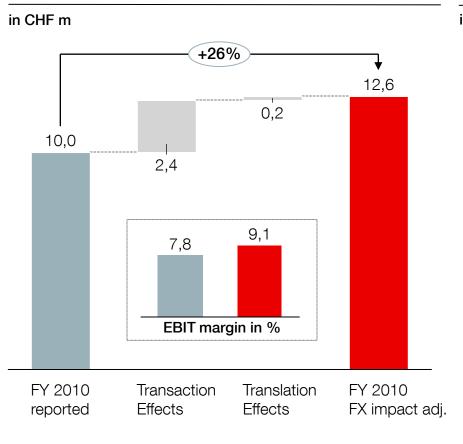
- Main sales currencies are USD and EUR
- Cost base predominantly in CHF

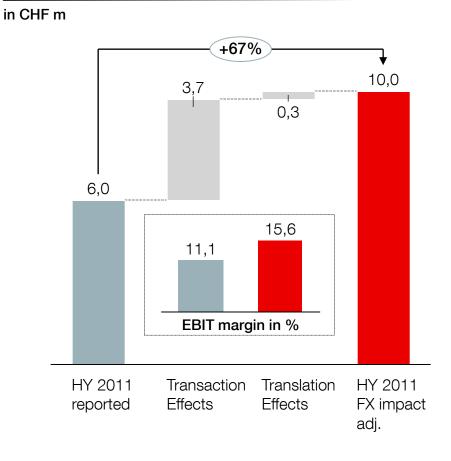
EBIT Margin significantly affected due to transaction and translation effects



Oerlikon Advanced Technologies EBIT FY 2010

Oerlikon Advanced Technologies EBIT H1 2011



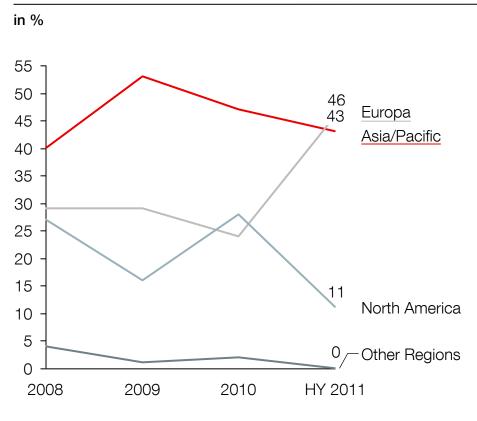


Main sales currencies are USD and EUR

Asia is main contributor to sales volume



Oerlikon Advanced Technologies Regional Sales Split 2008 – HY 2011

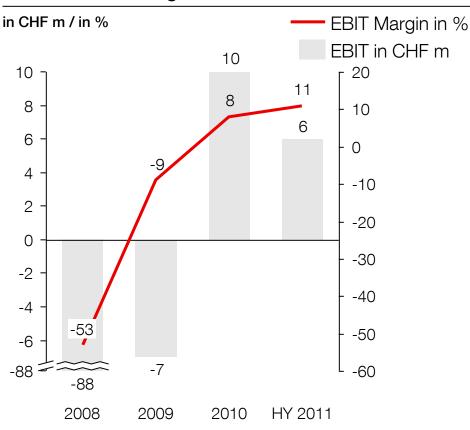


- Asia is the biggest contributor to regional sales volume in the years 2008 to 2010; about 50% of 2011 sales volume is expected to come from here
- EMEA sales were stable from 2008 2010; outlook for 2011 amounts to 35% of total sales.
- The US is expected to contribute 15% of overall sales in 2011

Back to profitability in 2010, strong HY 2011



EBIT and EBIT Margin 2008 - HY 2011



- 2008 result impacted by restructuring, divestments and impairments
- Results before restructuring and non recurring expenses was positive in 2009; divestments and restructuring projects sucessfully executed
- 2010 result driven by higher sales volume and significantly reduced cost base compared to previous year
- Strong HY 2011 result driven by successful implementation of COGS reduction programs and price increases

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Oerlikon Advanced Technologies - Summary



Technological Leadership

- Core competence in industrializing thin film coating applications
- Proven 50+ year track record
- Leading PVD source and process technology
- Highest productivity PVD tools for semi, optical disc and clean tech applications

Markets & Customers

- Supplier to all major players in semiconductor industry
- Focus on semiconductor market and clean tech applications
- Strong customer base in Asia

Operational Excellence

- Excellent reputation confirmed by independent market surveys
- Outstanding On Time Delivery
- Lean processes and organization

Tactics

- Differentiation: superior technology in selected semiconductor markets
- Enable commercialization of clean tech applications
- Incubator for Oerlikon Group



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